

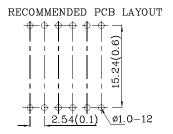
14.22mm (0.56") THREE DIGIT NUMERIC DIS-**PLAY**

Features

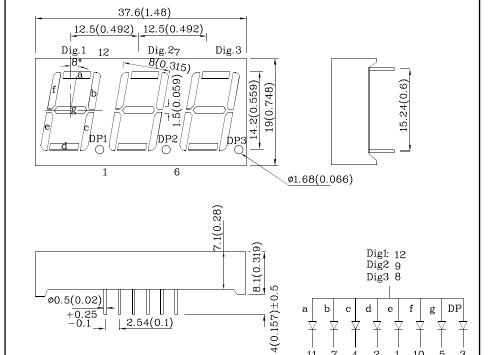
- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- ullet Optional black face provides superior color contrast
- RoHS Compliant







Package Schematics



1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

2.54(0.1)

Absolute Maximum Ratings $(T_A=25^{\circ}C)$	VG (AlGaInP)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	I _F 30		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	150	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]		260°C For 3-5 Seconds		

Operating Characteristics (T _A =25°C)	VG (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)		2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous CIE127 (I _F =10m	-2007*	Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDVG14A3	Green	AlGaInP	14000 5600*	34990 10990*	574*	Common Anode , Rt.Hand Decimal.

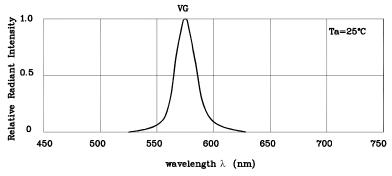
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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Part Number: XDVG14A3

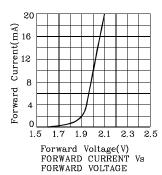
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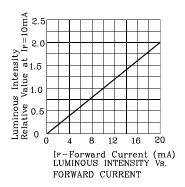


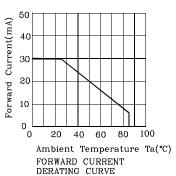


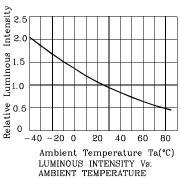
RELATIVE INTENSITY Vs. CIE WAVELENGTH

♦ VG

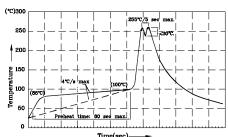








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a nocouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 260°C wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature oetwermax).
 3.Do not apply stress to the epoxy resin (-Pixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

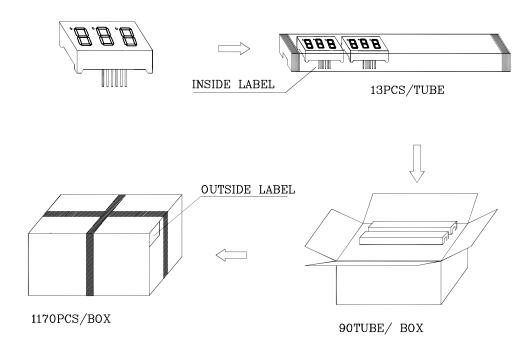
Note: Accuracy may depend on the sorting parameters.



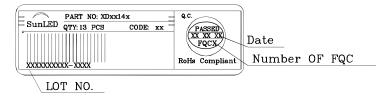
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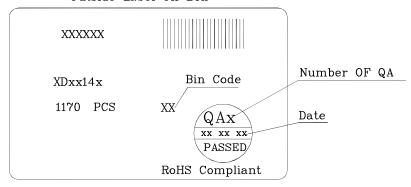
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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